

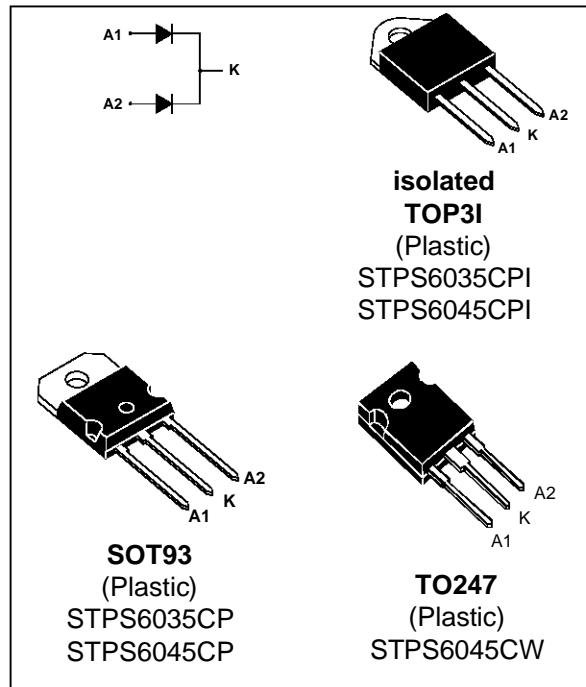
## POWER SCHOTTKY RECTIFIERS

- VERY SMALL CONDUCTION LOSSES
- NEGLIGIBLE SWITCHING LOSSES
- EXTREMELY FAST SWITCHING
- LOW FORWARD VOLTAGE DROP
- HIGH AVALANCHE CAPABILITY
- LOW THERMAL RESISTANCE
- INSULATED PACKAGE :
  - Insulating voltage = 2500V<sub>RMS</sub>
  - Capacitance = 12pF

**DESCRIPTION**

Dual center tap schottky rectifier suited for switchmode power supply and high frequency DC to DC converters.

Packaged in SOT93, TOP 3I or TO247 this device is intended for use in low voltage, high frequency inverters, free wheeling and polarity protection applications.


**ABSOLUTE RATINGS (limiting values)**

Symbol	Parameter			Value	Unit	
I <sub>F(RMS)</sub>	RMS Forward Current		Per diode	60	A	
I <sub>F(AV)</sub>	Average Forward Current δ = 0.5	SOT93/ TO247	T <sub>c</sub> = 125°C	Per diode	30	A
		TOP3I	T <sub>c</sub> = 105°C	Per device	60	
I <sub>FSM</sub>	Surge Non Repetitive Forward Current		T <sub>p</sub> = 10 ms Sinusoidal	Per diode	400	A
I <sub>RRM</sub>	Peak Repetitive Reverse Current		T <sub>p</sub> = 2 μs F = 1KHz	Per diode	1	A
T <sub>stg</sub> T <sub>j</sub>	Storage and Junction Temperature Range			- 65 to + 150 - 65 to + 150	°C	
dV/dt	Critical Rate of Rise of Reverse Voltage			1000	V/μs	

Symbol	Parameter	STPS		Unit
		6035CP 6035CPI	6045CP 6045CPI 6045CW	
V <sub>RRM</sub>	Repetitive Peak Reverse Voltage	35	45	V

## STPS6035CP/CPI / STPS6045CP/CPI / STPS6045CW

### THERMAL RESISTANCE

Symbol	Parameter			Value	Unit
$R_{TH(j-c)}$	Junction-case	SOT93 / TO2247	Per diode total	0.95 0.55	°C/W
		TOP3I	Per diode total	1.8 1.1	
$R_{TH(c)}$	Coupling	SOT93 / TO247		0.15	°C/W
		TOP3I		0.4	

When the diodes 1 and 2 are used simultaneously :

$$\Delta T_J(\text{diode 1}) = P(\text{diode 1}) \times R_{TH}(\text{Per diode}) + P(\text{diode 2}) \times R_{TH(c)}$$

### ELECTRICAL CHARACTERISTICS

#### STATIC CHARACTERISTICS PER DIODE

Symbol	Tests Conditions		Min.	Typ.	Max.	Unit
$I_R$ *	$T_j = 25^\circ\text{C}$	$V_R = V_{RRM}$			500	$\mu\text{A}$
	$T_j = 125^\circ\text{C}$				80	mA
$V_F$ **	$T_j = 125^\circ\text{C}$	$I_F = 60 \text{ A}$			0.78	V
	$T_j = 125^\circ\text{C}$	$I_F = 30 \text{ A}$			0.63	
	$T_j = 25^\circ\text{C}$	$I_F = 60 \text{ A}$			0.84	

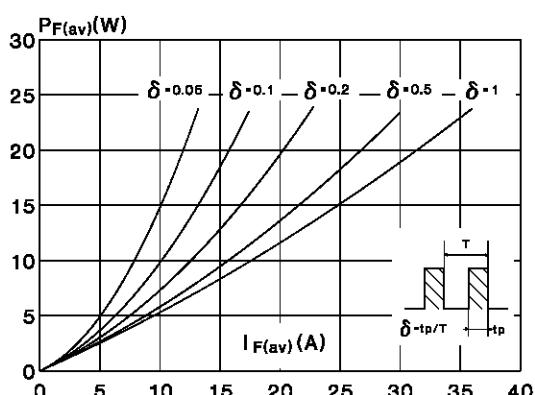
Pulse test : \*  $t_p = 5 \text{ ms}$ , duty cycle < 2 %

\*\*  $t_p = 380 \mu\text{s}$ , duty cycle < 2%

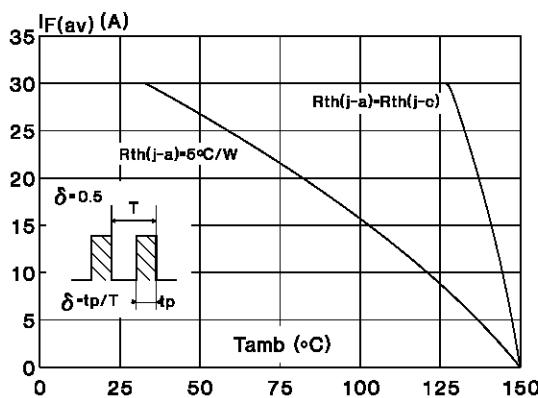
To evaluate the conduction losses use the following equation :

$$P = 0.48 \times I_{F(AV)} + 0.005 I_{F(RMS)}^2$$

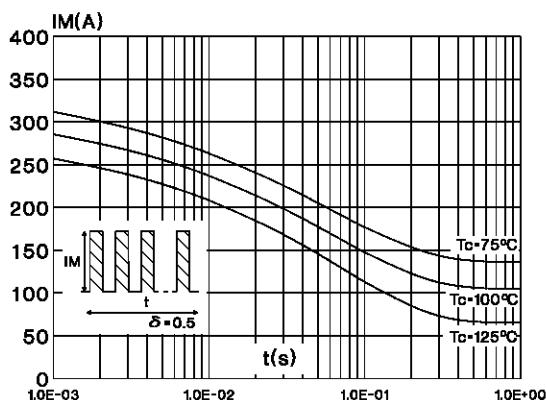
**Fig. 1 :** Average forward power dissipation versus average forward current. (Per diode)



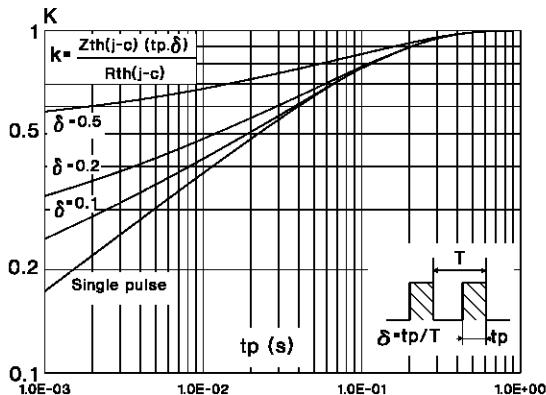
**Fig. 2 :** Average current versus ambient temperature.(duty cycle : 0.5) (per diode) (SOT93 and TO247)



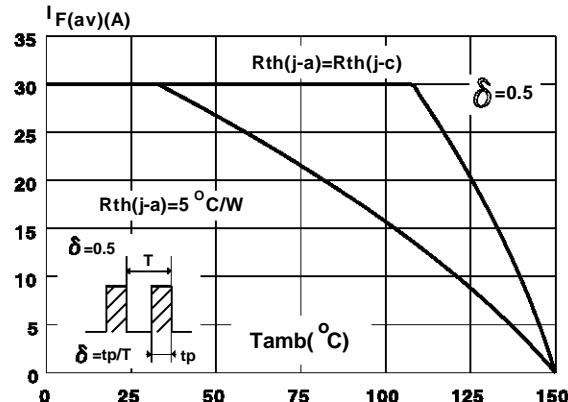
**Fig. 4 :** Non repetitive surge peak forward current versus overload duration.  
(Maximum values) (Per diode) (SOT93 and TO247)



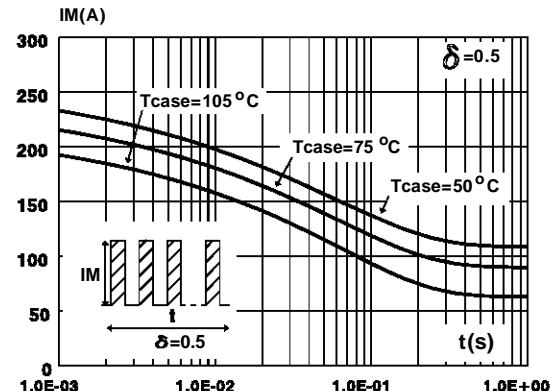
**Fig. 6 :** Relative variation of thermal transient impedance junction to case versus pulse duration.



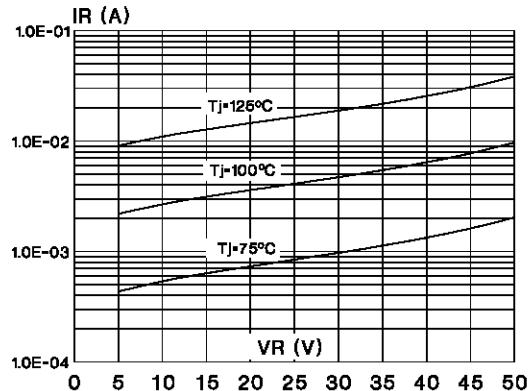
**Fig. 3 :** Average current versus ambient temperature.(duty cycle : 0.5) (per diode) (TOP3I)



**Fig. 5 :** Non repetitive surge peak forward current versus overload duration.  
(Maximum values) (Per diode) (TOP3I)



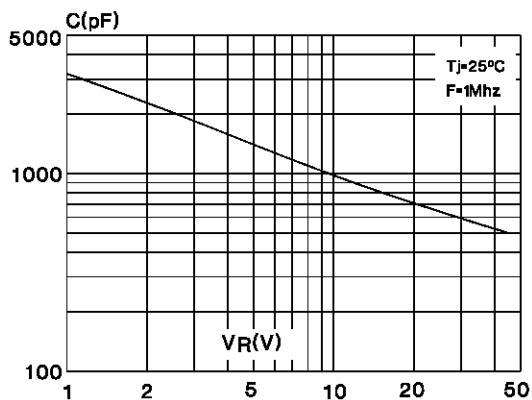
**Fig. 7 :** Reverse leakage current versus reverse voltage applied. (Typical values) (Per diode)



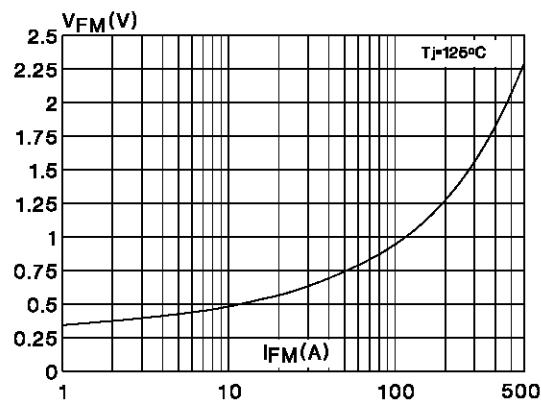
## **STPS6035CP/CPI / STPS6045CP/CPI / STPS6045CW**

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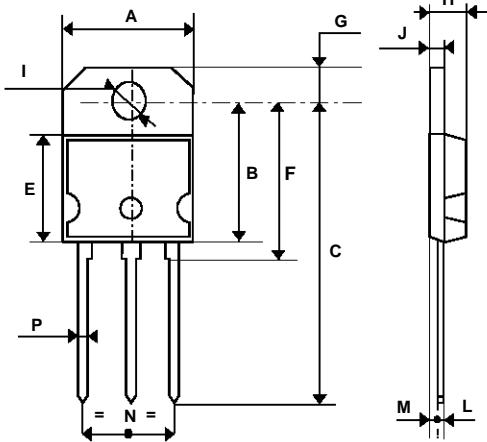
**Fig. 8 :** Junction capacitance versus reverse voltage applied. (Typical values) (Per diode)



**Fig. 9 :** Forward voltage drop versus forward current. (Maximum values) (Per diode)



**PACKAGE MECHANICAL DATA**  
SOT93



REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	14.7	15.2	0.578	0.596
B		16.2		0.637
C	31 typ		1.220 typ	
D	18 typ		0.708 typ	
E		12.2		0.480
G	3.95	4.15	0.155	0.163
H	4.7	4.9	0.185	0.193
I	4	4.1	0.157	0.161
J	1.9	2.1	0.062	0.075
L	0.5	0.78	0.019	0.030
M	2.5 typ		0.098 typ	
N	10.8	11.1	0.425	0.437
P	1.1	1.3	0.043	0.051

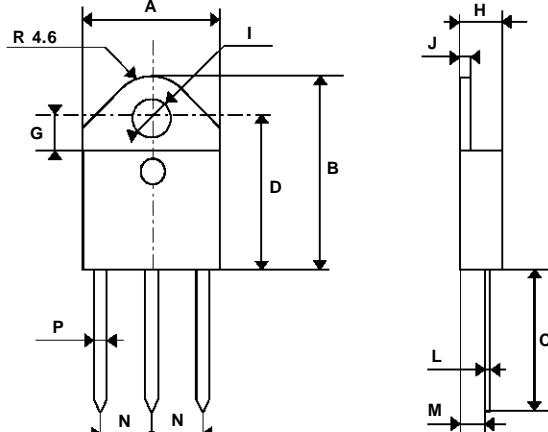
Cooling method : C

Marking : Type number

Weight : 5.3 g

Recommended torque value : 0.8m.N

**PACKAGE MECHANICAL DATA**  
TOP3I (isolated)



REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	15.10	15.50	0.594	0.611
B	20.70	21.10	0.814	0.831
C	14.30	15.60	0.561	0.615
D	16.10	16.50	0.632	0.650
G	3.40	-	0.133	-
H	4.40	4.60	0.173	0.182
I	4.08	4.17	0.161	0.164
J	1.45	1.55	0.057	0.062
L	0.50	0.70	0.019	0.028
M	2.70	2.90	0.106	0.115
N	5.40	5.65	0.212	0.223
P	1.20	1.40	0.047	0.056

Cooling method : C

Marking : Type number

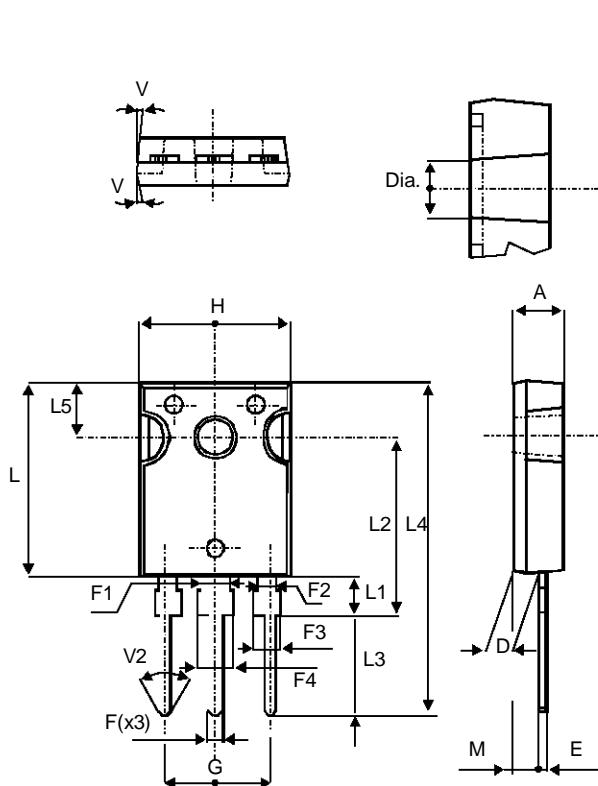
Weight : 4.7 g

Recommended torque value : 0.8m.N

Maximum torque value : 1.0m.N

## STPS6035CP/CPI / STPS6045CP/CPI / STPS6045CW

### PACKAGE MECHANICAL DATA TO247



REF.	DIMENSIONS					
	Millimeters			Inches		
	Typ.	Min.	Max.	Typ.	Min.	Max.
A	4.70	5.30		0.190	0.210	
D	2.20	2.60		0.086	0.102	
E	0.40	0.80		0.015	0.031	
F	1.00	1.40		0.039	0.055	
F1	3.00			0.118		
F2	2.00			0.078		
F3		2.00	2.40		0.078	0.094
F4		3.00	3.40		0.118	0.133
G	10.90			0.429		
H		15.30	15.90		0.602	0.625
L		19.70	20.30		0.775	0.799
L1	3.70	4.30		0.145	0.169	
L2	18.50			0.728		
L3	10.50			0.413		
L4	34.60			1.362		
L5	5.50			0.216		
M		2.00	3.00		0.078	0.118
V	5°			5°		
V2	60°			60°		
Dia.		3.55	3.65		0.139	0.143

Cooling method : C

Marking : Type number

Weight : 4.4 g

Recommended torque value : 0.8m.N

Maximum torque value : 1.0m.N

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